

Title (en)

Catalyst for electroless plating process.

Title (de)

Katalysator für die stromlose Plattierung.

Title (fr)

Catalyseur pour dépôt chimique.

Publication

**EP 0317092 A1 19890524 (EN)**

Application

**EP 88310037 A 19881026**

Priority

GB 8725148 A 19871027

Abstract (en)

Complexes comprising X palladium atoms and Y nitrogen-containing ligands wherein  $X/Y \geq 1$  are useful as sensitisers in rendering substrates catalytic to the deposition of electroless metal. The compounds can be prepared by reacting A moles of a nitrogen-containing compound with B moles of palladium where  $A/B \leq 4$  at a pH of 6 or above.

IPC 1-7

**C23C 18/28**

IPC 8 full level

**C23C 18/28** (2006.01); **C23C 18/30** (2006.01); **C23C 18/38** (2006.01)

CPC (source: EP)

**C23C 18/28** (2013.01)

Citation (search report)

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- [X] FR 2132172 A1 19721117 - SCHERING AG
- [A] FR 1481700 A 19670519 - PHOTOCIRCUITS CORP
- [X] PATENT ABSTRACTS OF JAPAN, vol. 9, no. 166 (C-290)[1889], 11th July 1985; & JP-A-60 36 672 (HITACHI KASEI KOGYO K.K.) 25-02-1985
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